





#### SURFACE MOUNT FAST SWITCHING DIODE

### **Features**

- Fast Switching Speed
- Small Surface Mount Package
- For General Purpose Switching Applications
- **High Conductance**
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 3)
- "Green" Device (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOD-323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Leads: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.004 grams (approximate)



Top View

### **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic   |                           | Symbol  | Value    | Unit |
|--|---------------------------|---|----------|------|
| Non-Repetitive Peak Reverse Voltage  |                           | $V_{RM}$  | 100      | V    |
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage |                           | V <sub>RRM</sub><br>V <sub>R</sub> WM<br>V <sub>R</sub> | 75       | V    |
| RMS Reverse Voltage  |                           | V <sub>R(RMS)</sub>                                     | 53       | V    |
| Forward Continuous Current   |                           | I <sub>FM</sub>   | 500      | mA   |
| Average Rectified Output Current   |                           | I <sub>O</sub>  | 250      | mA   |
| Non-Repetitive Peak Forward Surge Current  | @ t = 1.0μs<br>@ t = 1.0s | I <sub>FSM</sub>  | 4<br>0.5 | А    |

### Thermal Characteristics

| Characteristic                                      | Symbol                            | Value       | Unit |
|---|-----------------------------------|-------------|------|
| Power Dissipation (Note 2)                          | P <sub>D</sub>                    | 200         | mW   |
| Thermal Resistance Junction to Ambient Air (Note 2) | $R_{	heta JA}$                    | 625         | °C/W |
| Operating and Storage Temperature Range             | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 | °C   |

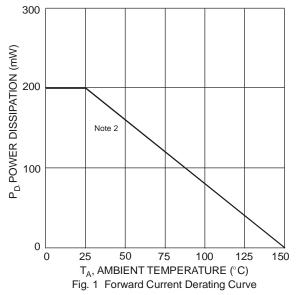
## **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

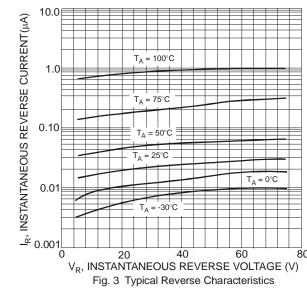
| Characteristic                     | Symbol          | Min               | Max   | Unit | Test Condition                               |
|------------------------------------|-----------------|-------------------|-------|------|--|
| Reverse Breakdown Voltage (Note 1) | $V_{(BR)R}$     | 75                | _     | V    | $I_R = 2.5 \mu A$                            |
|                                    |                 | 0.62              | 0.72  |      | I <sub>F</sub> = 5.0mA                       |
| Forward Voltage                    | \/              | _                 | 0.855 |      | $I_F = 10 \text{mA}$                         |
| orward voltage                     | $V_{FM}$        | _                 | 1.0   |      | I <sub>F</sub> = 100mA                       |
|                                    |                 | _                 | 1.25  |      | I <sub>F</sub> = 150mA                       |
|                                    |                 | I <sub>RM</sub> — | 2.5   | μΑ   | V <sub>R</sub> = 75V                         |
| Peak Reverse Current (Note 1)      | 1               |                   | 50    | μA   | V <sub>R</sub> = 75V, T <sub>J</sub> = 150°C |
| reak Neverse Guiteiii (Note 1)     | IRM             |                   | 30    | μΑ   | $V_R = 25V, T_J = 150^{\circ}C$              |
|                                    |                 |                   | 25    | nA   | $V_R = 20V$                                  |
| Total Capacitance                  | C <sub>T</sub>  | _                 | 4.0   | pF   | V <sub>R</sub> = 0, f = 1.0MHz               |
| Poverse Pecevery Time              |                 |                   | 4.0   | ns   | $I_F = I_R = 10 \text{mA},$                  |
| Reverse Recovery Time              | t <sub>rr</sub> | _                 |       |      | $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$   |

Notes:

- 1. Short duration pulse test used to minimize self-heating.
- 2. Part mounted on FR-4 PC board with minimum recommended pad layouts, which can be found on our website at http://www/diodes.com/datasheets/ap02001.pdf.
- 3. No purposefully added lead. Halogen and Antimony Free.
- 4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.







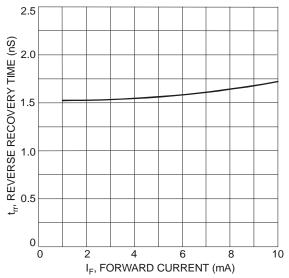
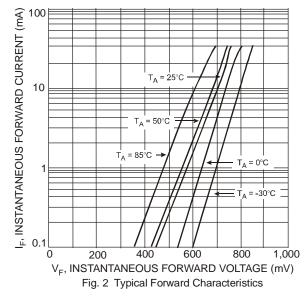
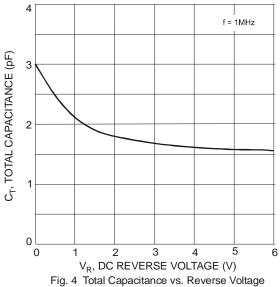


Fig. 5 Reverse Recovery Time vs. Forward Current







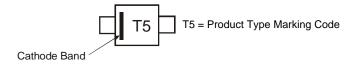
## Ordering Information (Note 5)

| Part Number  | Case    | Packaging        |
|--------------|---------|------------------|
| 1N4448WS-7-F | SOD-323 | 3000/Tape & Reel |

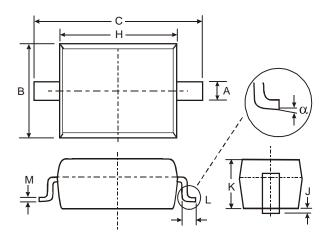
Notes:

5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**

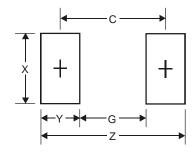


## **Package Outline Dimensions**



| SOD-323              |      |      |  |  |
|----------------------|------|------|--|--|
| Dim                  | Min  | Max  |  |  |
| Α                    | 0.25 | 0.35 |  |  |
| В                    | 1.20 | 1.40 |  |  |
| С                    | 2.30 | 2.70 |  |  |
| Н                    | 1.60 | 1.80 |  |  |
| J                    | 0.00 | 0.10 |  |  |
| K                    | 1.0  | 1.1  |  |  |
| L                    | 0.20 | 0.40 |  |  |
| М                    | 0.10 | 0.15 |  |  |
| α                    | 0°   | 8°   |  |  |
| All Dimensions in mm |      |      |  |  |

# Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 3.75          |
| G          | 1.05          |
| Х          | 0.65          |
| Υ          | 1.35          |
| С          | 2.40          |



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